

GTXO-C73 - 3.3 & 5V Stratum 3 CMOS TCXO

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
XR Crystal	Kovar Lid	Si	7440-21-3	0.032	0.60
	Kovar Lid	Co	7440-48-4	0.053	0.99
	Kovar Lid	Mn	7439-96-5	0.085	1.60
	Kovar Lid	Ni	7440-02-0	5.159	96.81
Adhesive	Adhesive	Epoxy resin trade secret	0	0.250	25.00
	Ag	Ag	7440-22-4	0.750	75.00
Base	Base Metalisation	W	7440-33-7	7.240	7.21
	Ceramic	TiO2	13463-67-7	1.833	1.82
	Ceramic	Cr2O3	1308-38-9	3.668	3.65
	Ceramic	SiO2	14808-60-7	3.668	3.65
	Ceramic	Al2O3	1344-28-1	82.503	82.13
	Plate	Au	7440-57-5	0.410	0.41
	Plate	Ni	7440-02-0	1.130	1.12
Capacitors	Ceramic	BaTiO3	12047-27-7	2.432	73.70
	Electrode material	Ni	7440-02-0	0.100	3.03
	Electrode material	Cu	7440-50-8	0.480	14.55
	Plate	Ni	7440-02-0	0.160	4.85
	Plate	Sn	7440-31-5	0.128	3.88
Crystal	Adhesive	SiO2	14808-60-7	0.080	0.13
	Adhesive	Si	7440-21-3	1.694	2.76
	Adhesive	Resin		0.080	0.13
	Adhesive	Ag	7440-22-4	0.640	1.04
	Base Metalisation	W	7440-33-7	5.650	9.20
	Base Pin	Co	7440-48-4	0.979	1.59
	Base Pin	Fe	7439-89-6	2.878	4.69
	Base Plate	Au	7440-57-5	0.240	0.39
	Base ceramic	Cr2O3	1308-38-9	0.771	1.26
	Base ceramic	Mo	7439-98-7	0.771	1.26
	Base ceramic	SiO2	14808-60-7	2.317	3.77
	Base ceramic	Al2O3	1344-28-1	34.758	56.58
	Blank	SiO2	14808-60-7	1.200	1.95
	Electrode material	Ni	7440-02-0	0.030	0.05
	Electrode material	Au	7440-57-5	0.270	0.44
	Kovar Lid	Fe	7439-89-6	5.999	9.77
	Lid plate	Ni	7440-02-0	0.690	1.12
	Solder	Cu	7440-50-8	0.690	1.12
	Solder	Ag	7440-22-4	1.690	2.75
	IC	IC	Si	7440-21-3	1.994
IC Al		Al	7429-90-5	0.006	0.30
Solder	Antimony	Sb	7440-36-0	0.120	4.00
	Flux trade secret	Flux trade secret	0	0.330	11.00

Material Composition Data



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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Solder	Tin	Sn	7440-31-5	2.550	85.00
Wire	Gold	Au	7440-57-5	0.100	100.00
XR Crystal	Kovar Lid	C	7440-44-0	0.002	100.00
Total Mass:				176.610 mg	

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